

TITLE: SINGLE AND MULTIPLE LAYER PKGNG. OF HIGH-SPEED/HIGH-DENSITY ICs
INVENTOR'S NAME: BINNEG Y. LAO, ET. AL
APPLICATION NO.: 09/990,247
DOCKET NO.: 89252.0005

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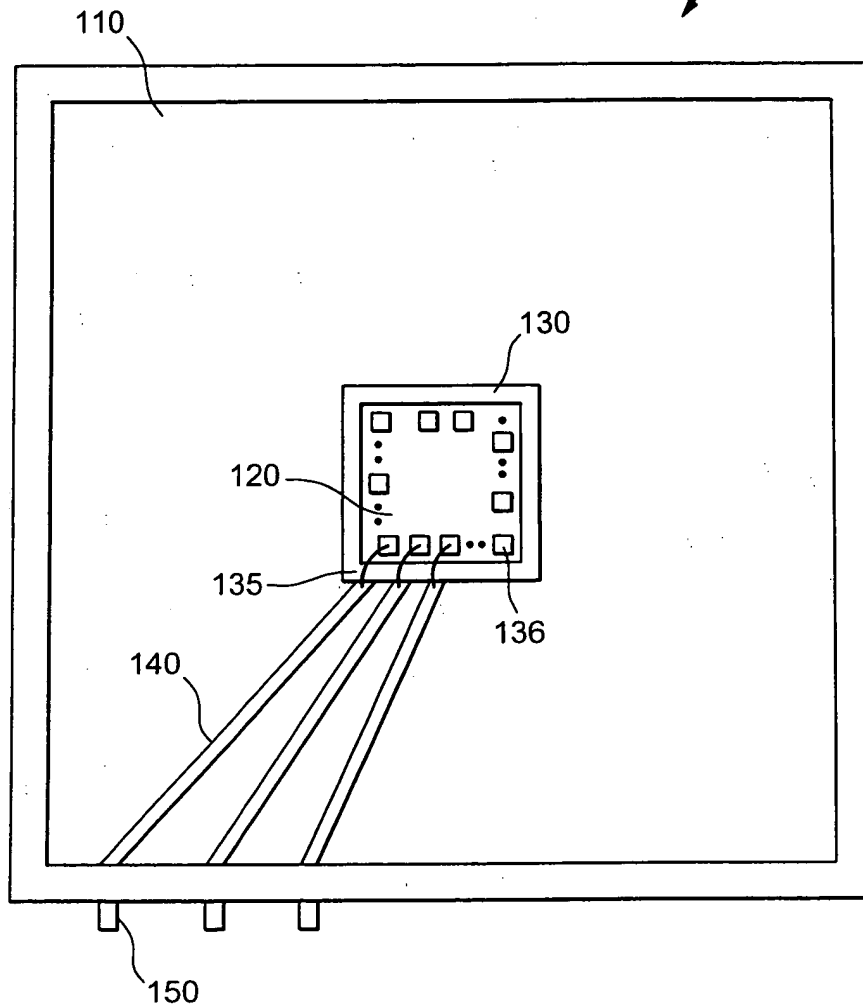
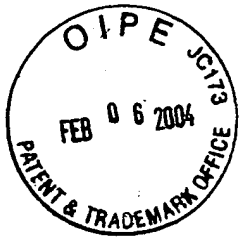


FIG. 1
(PRIOR ART)



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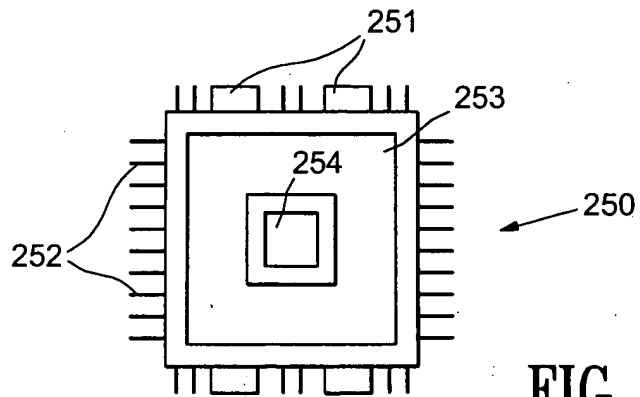


FIG. 2

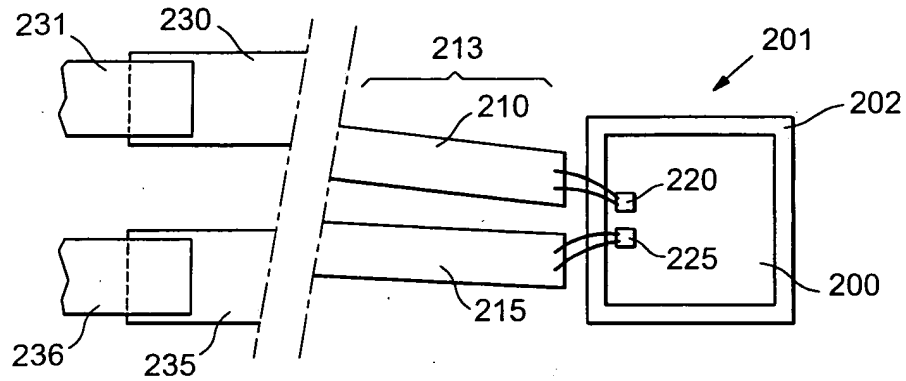


FIG. 3(a)

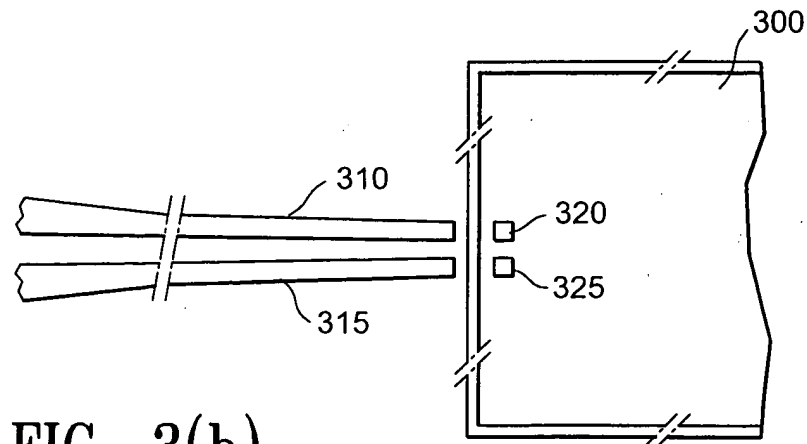
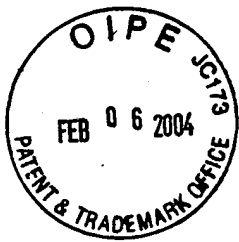


FIG. 3(b)



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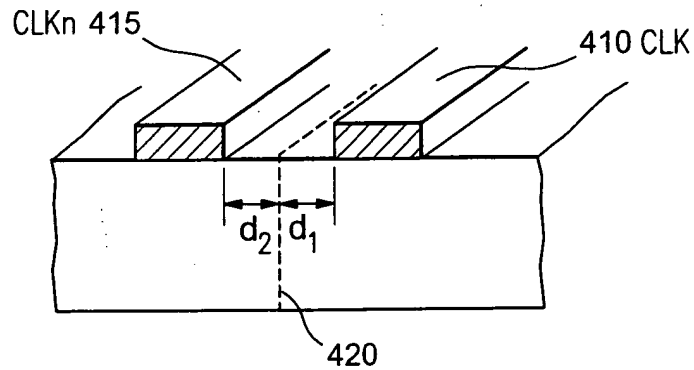


FIG. 4(a)

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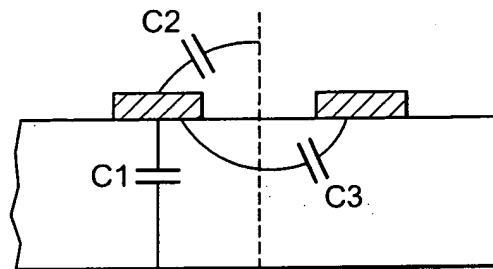


FIG. 4(b)

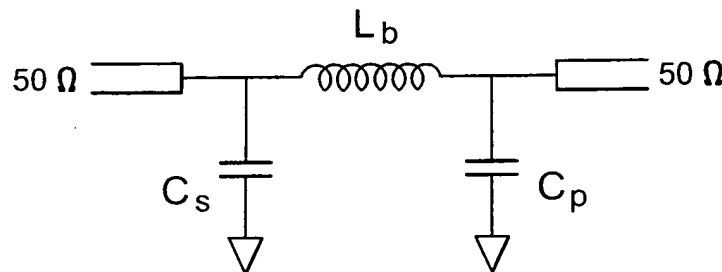
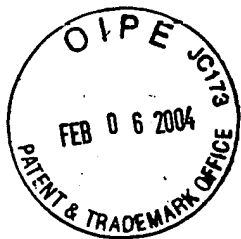


FIG. 5



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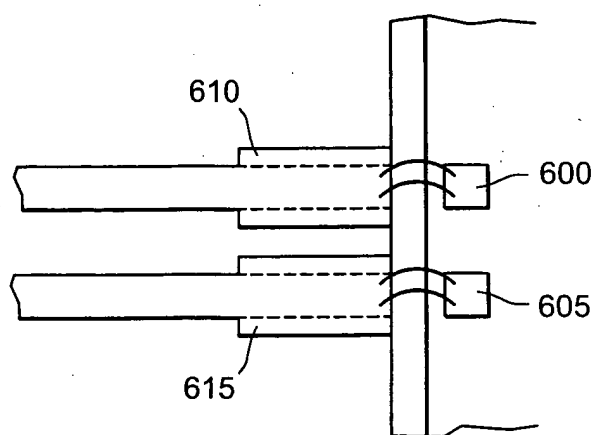


FIG. 6

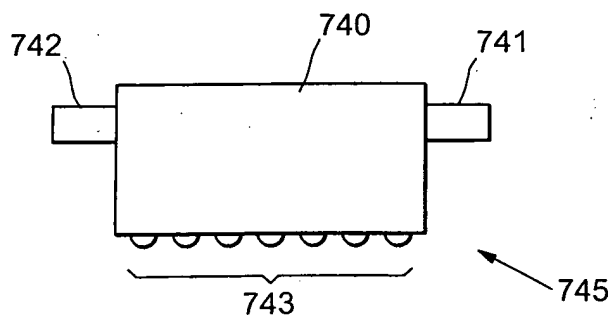
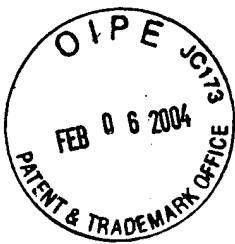


FIG. 7

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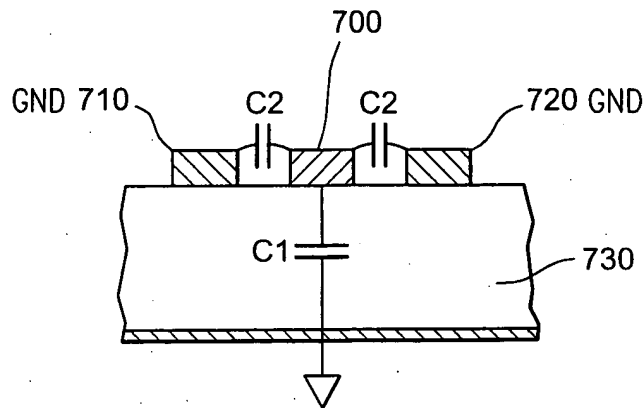


FIG. 8

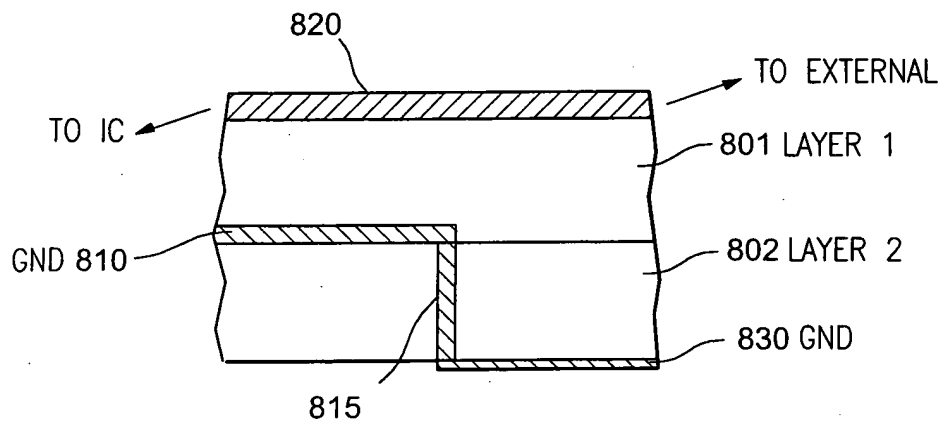


FIG. 9(a)

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Replacement Sheet

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FIG. 9(b)(1)

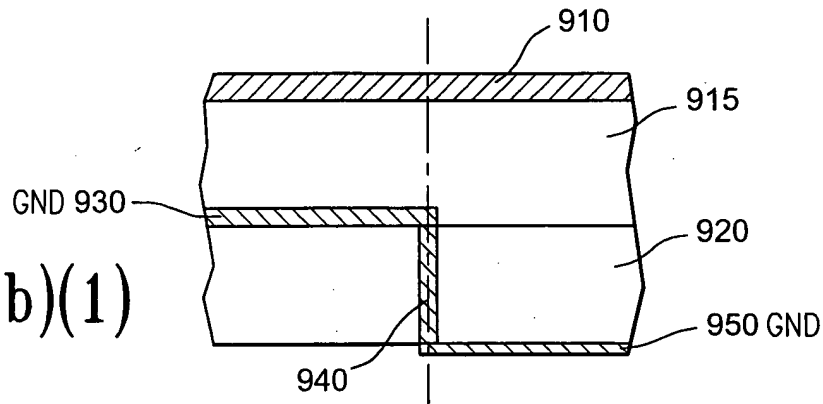
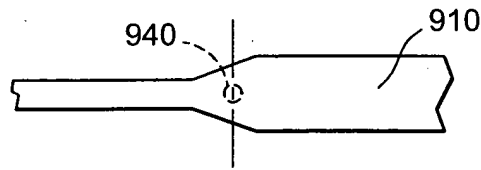


FIG. 9(b)(2)



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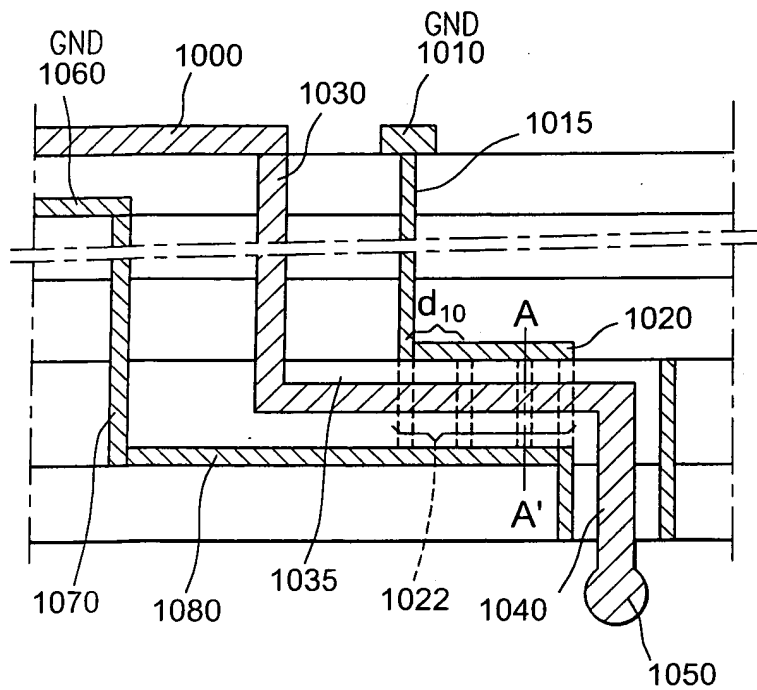


FIG. 10(a)

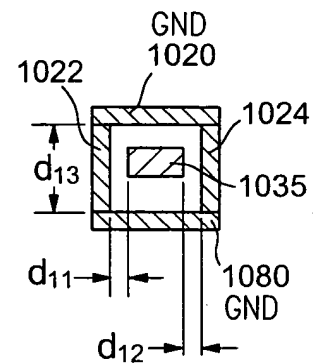
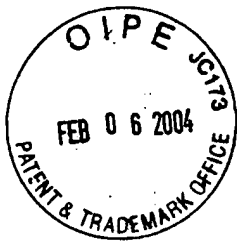


FIG. 10(b)



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FIG. 10(c)

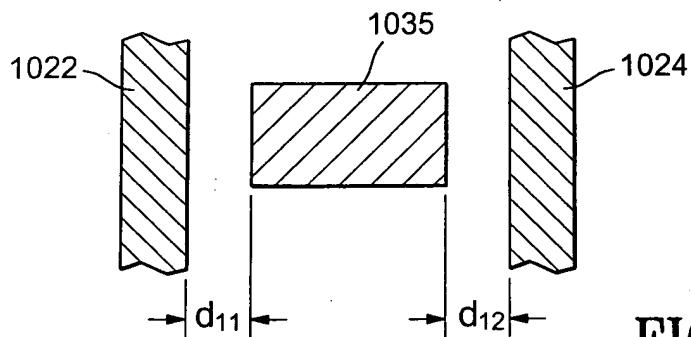
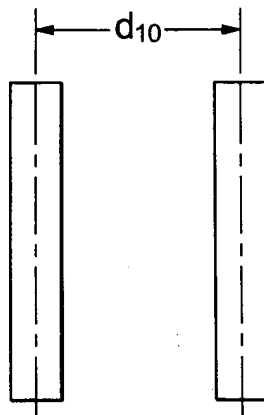


FIG. 10(d)

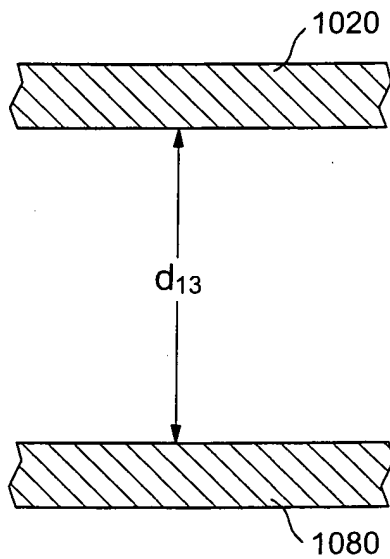
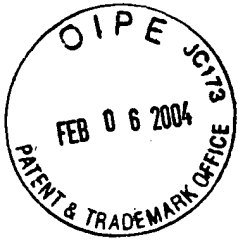


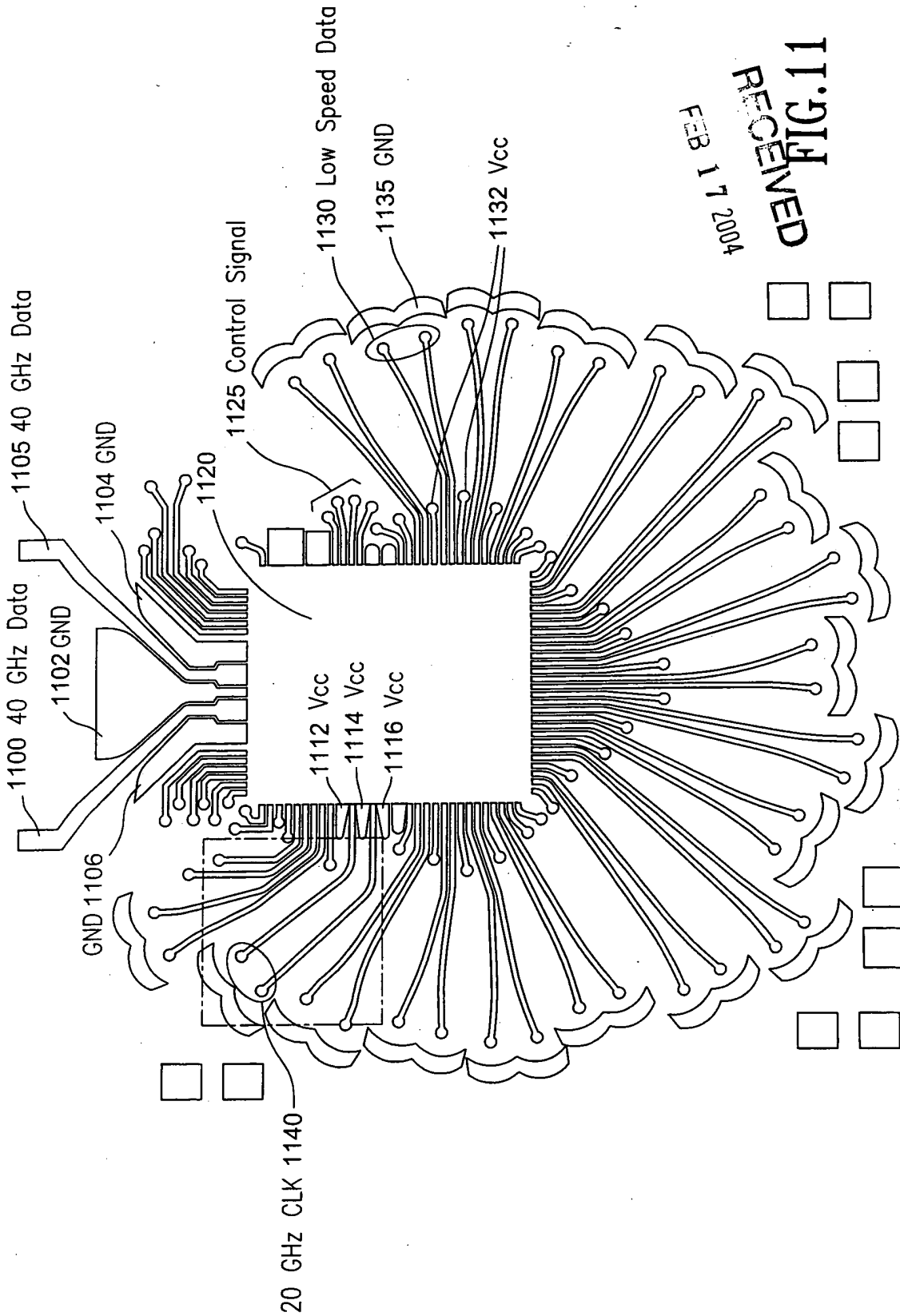
FIG. 10(e)

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FIG. 11



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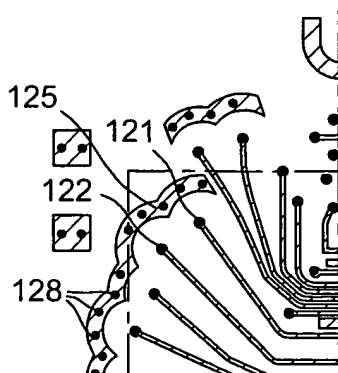


FIG. 12(a)

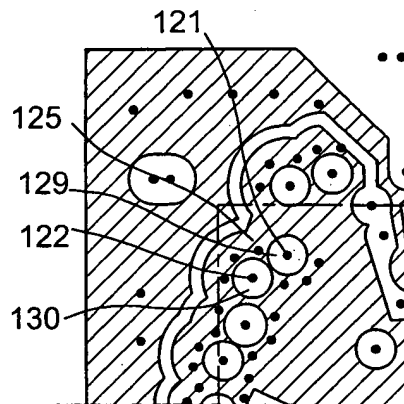


FIG. 12(b)

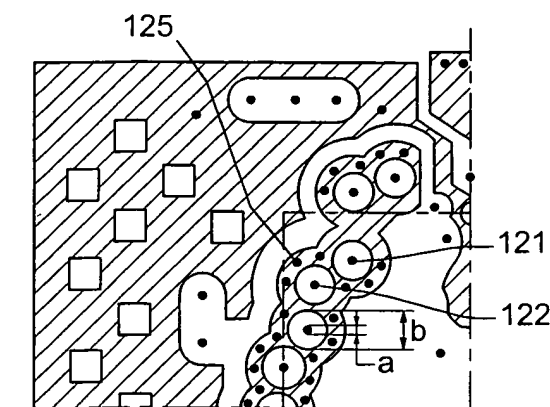


FIG. 12(c)

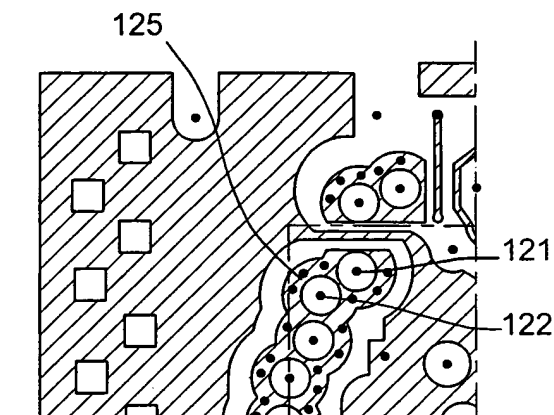


FIG. 12(d)

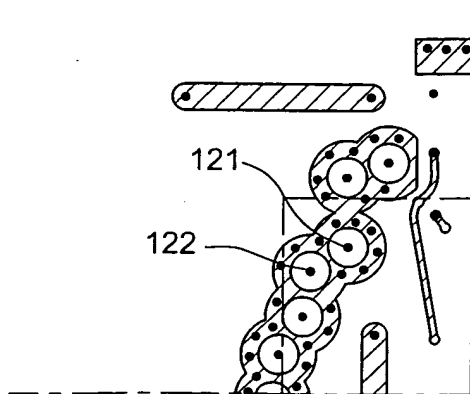


FIG. 12(e)

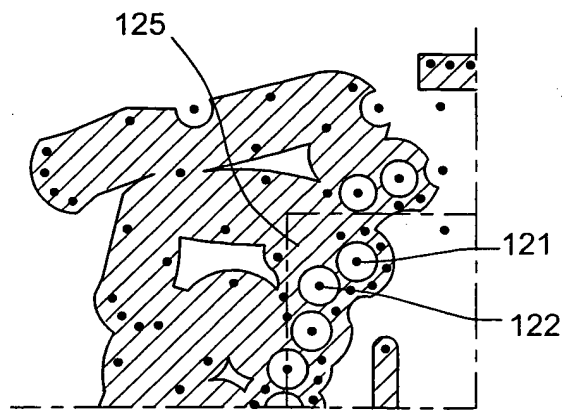
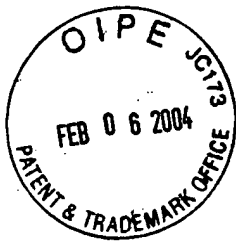


FIG. 12(f)

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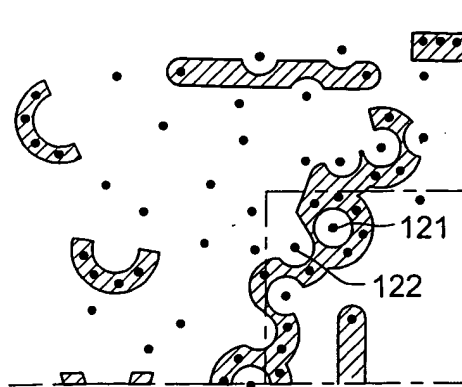


FIG. 12(g)

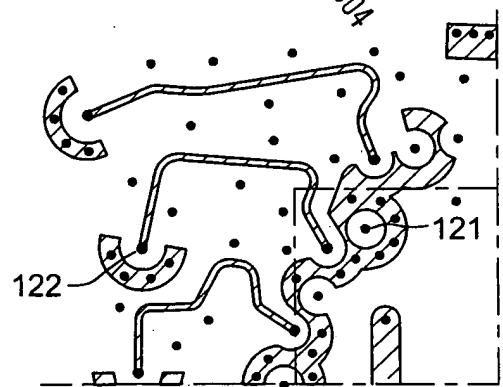


FIG. 12(h)

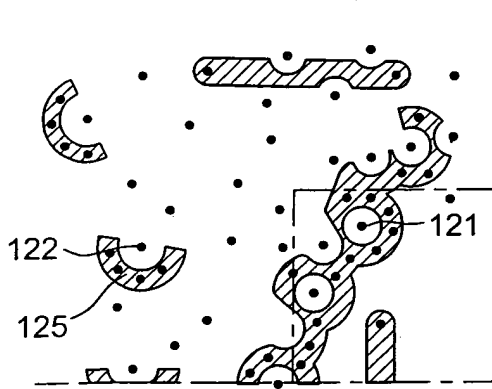


FIG. 12(i)

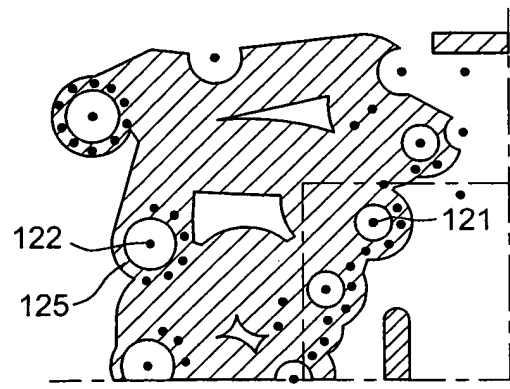


FIG. 12(j)

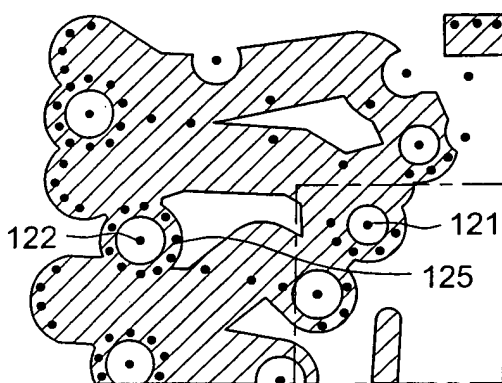


FIG. 12(k)

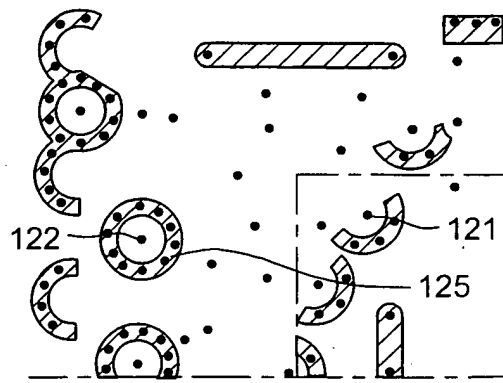
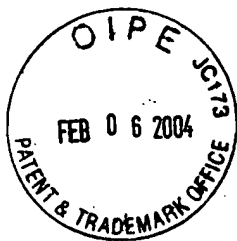


FIG. 12(l)

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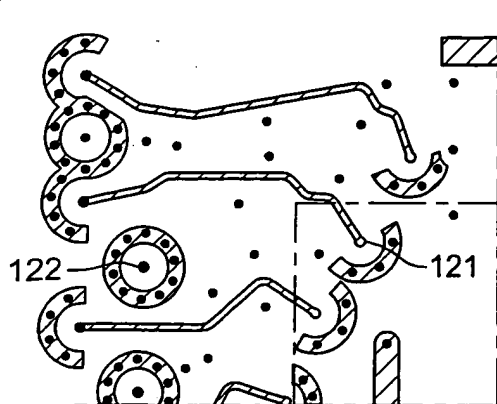


FIG. 12(m)

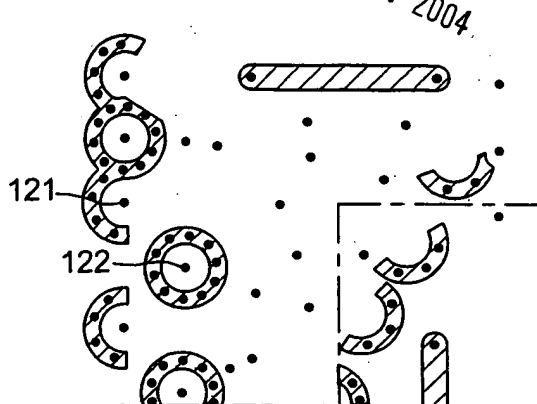


FIG. 12(n)

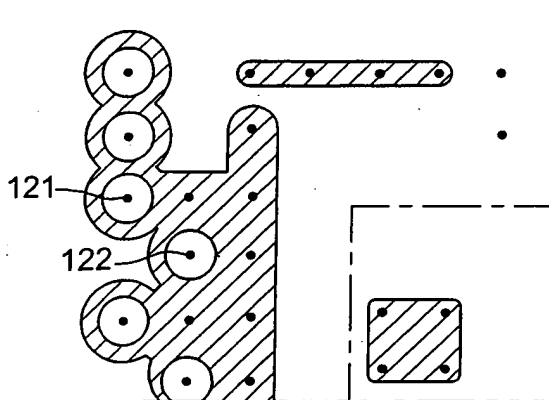


FIG. 12(o)

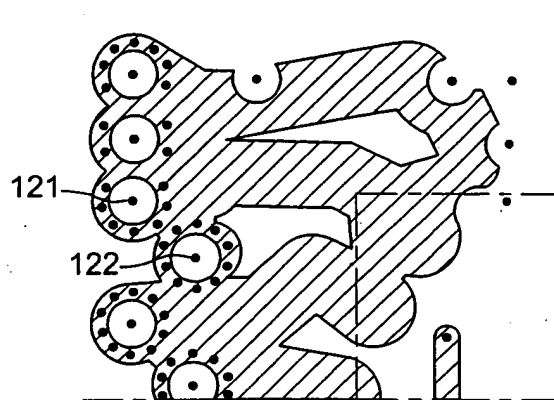


FIG. 12(p)

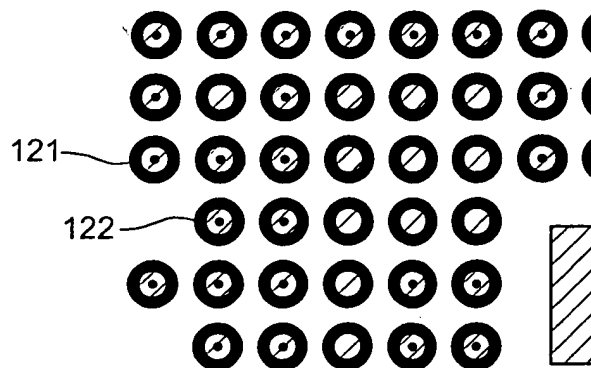


FIG. 12(q)